



CHONGQING CLOUDCHILD TECHNOLOGY CO.,LTD

**DFN5\*6-10L Plastic-Encapsulate MOSFETS**

**CCM4E20D04T N+P Channel Power MOSFET**

	N-CHANNEL	P-CHANNEL
$V_{DS}$ (V)	40	-40
$R_{DS(on)}$ (m $\Omega$ ) at $V_{GS} = \pm 10$ V	16	26
$R_{DS(on)}$ (m $\Omega$ ) at $V_{GS} = \pm 4.5$ V	25	38
$I_D$ (A)	20	-20

**DESCRIPTION**

The CCM4E20D04T provides excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications .

**FEATURES**

- TrenchFET® Power MOSFET
- 100 %  $R_g$  and UIS Tested
- AEC Q101 qualified

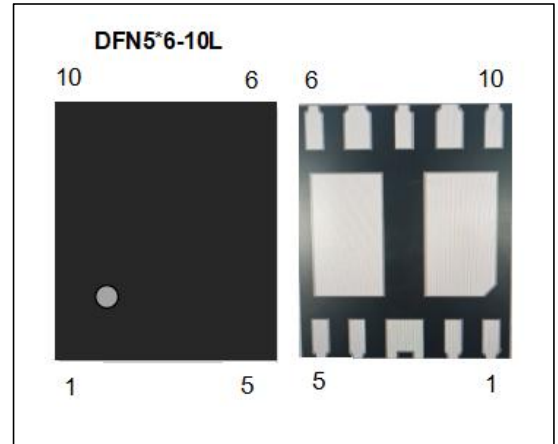
**APPLICATIONS**

- Bridge drive
- Single phase AC motor drive
- High-frequency switching

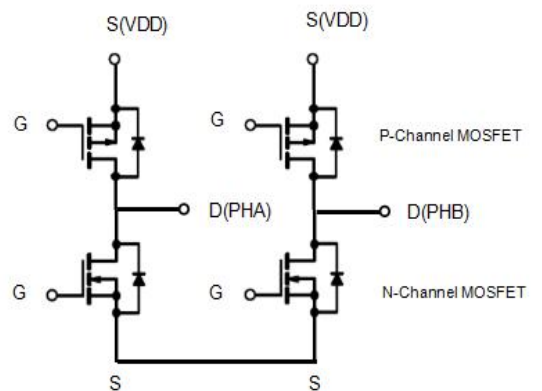
**MARKING**



CCM4E20D04T =Part No.  
XXXXXXX = Code.



**EQUIVALENT CIRCUIT**



## PIN DEFINITION

Number	Pin Definition	Remark
1	GLA	Lower bridge A phase N-channel gate
2	PHA(DHA/DLA)	A phase output(Upper bridge A phase P-channel drain/Lower bridge A phase N-channel drain)
3	LS(SLA/SLB)	Lower bridge A phase and B phase N-channel source
4	PHB(DHB/DLB)	B phase output(Upper bridge B phase P-channel drain/Lower bridge B phase N-channel drain)
5	GLB	Lower bridge B phase N-channel gate
6	GHB	Upper bridge B phase P-channel gate
7	VDD(SHB)	DC Input(Upper bridge B phase P-channel source)
8	LS(SLA/SLB)	Lower bridge A phase and B phase N-channel source
9	VDD(SHA)	DC Input(Upper bridge A phase P-channel source)
10	GHA	Upper bridge A phase P-channel gate

## ABSOLUTE MAXIMUM RATINGS( $T_c=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	N-CHANNEL	P-CHANNEL	Unit
Drain-Source Voltage	$V_{DS}$	40	-40	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$		
Continuous Drain Current <sup>1</sup>	$I_D$	20	-20	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	80	-80	
Single Pulse Avalanche Energy <sup>3</sup>	$E_{AS}$	25		mJ
Maximum Power Dissipation <sup>2</sup>	$P_D$	60		W
Thermal Resistance from Junction to Case	$R_{\theta JC}$	2.5		$^{\circ}\text{C/W}$
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	62		$^{\circ}\text{C/W}$
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55~ +175		$^{\circ}\text{C}$
Soldering Temperature , for 10S(1.6mm from case)	-	260		$^{\circ}\text{C}$

### Notes:

- 1.Package limited.
- 2.Pulse test; pulse width  $\leq 300 \mu\text{s}$ , duty cycle  $\leq 2 \%$ .
3. EAS condition:  $V_{DD}=20\text{V}, V_{GS}=10\text{V}, I_D=10\text{A}, L=0.5\text{mH}, R_g=25\Omega$  Starting  $T_J = 25^{\circ}\text{C}$ .

# MOSFET ELECTRICAL CHARACTERISTICS(TC=25°C unless otherwise specified)

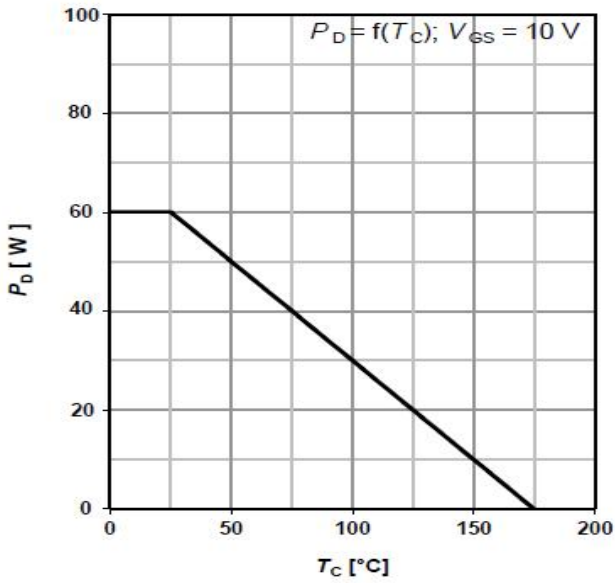
Parameter	Symbol	Test Condition		Min	Typ	Max	Unit	
<b>Off characteristics</b>								
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$		N-Ch	40		V	
		$V_{GS} = 0\text{ V}, I_D = -250\ \mu\text{A}$		P-Ch	-40			
Gate-Source Leakage	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$		N-Ch	-	$\pm 100$	nA	
				P-Ch	-	$\pm 100$		
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{GS} = 0\text{ V}$	$V_{DS} = 40\text{ V}$	N-Ch	-	1	$\mu\text{A}$	
		$V_{GS} = 0\text{ V}$	$V_{DS} = -40\text{ V}$	P-Ch	-	-1		
<b>On characteristics</b>								
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\ \mu\text{A}$		N-Ch	1.0	1.5	2.0	V
		$V_{DS} = V_{GS}, I_D = -250\ \mu\text{A}$		P-Ch	-1.1	-1.6	-2.2	V
Drain-Source On-State Resistance <sup>1</sup>	$R_{DS(on)}$	$V_{GS} = 10\text{ V}$	$I_D = 1\text{ A}$	N-Ch	-	20	25	mΩ
		$V_{GS} = -10\text{ V}$	$I_D = -1\text{ A}$	P-Ch	-	30	35	
		$V_{GS} = 4.5\text{ V}$	$I_D = 1\text{ A}$	N-Ch	-	25	32	
		$V_{GS} = -4.5\text{ V}$	$I_D = -1\text{ A}$	P-Ch	-	40	45	
Forward Transconductance <sup>2</sup>	$g_{fs}$	$V_{DS} = 10\text{ V}, I_D = 10\text{ A}$		N-Ch	-	26	-	S
		$V_{DS} = -10\text{ V}, I_D = -10\text{ A}$		P-Ch	-	25	-	
<b>Dynamic characteristics<sup>2</sup></b>								
Input Capacitance	$C_{iss}$	$V_{GS} = 0\text{ V}$	$V_{DS} = 25\text{ V}, f = 1\text{ MHz}$	N-Ch	-	775		pF
		$V_{GS} = 0\text{ V}$	$V_{DS} = -25\text{ V}, f = 1\text{ MHz}$	P-Ch	-	1490		
Output Capacitance	$C_{oss}$	$V_{GS} = 0\text{ V}$	$V_{DS} = 25\text{ V}, f = 1\text{ MHz}$	N-Ch	-	55		pF
		$V_{GS} = 0\text{ V}$	$V_{DS} = -25\text{ V}, f = 1\text{ MHz}$	P-Ch	-	100		
Reverse Transfer Capacitance	$C_{rss}$	$V_{GS} = 0\text{ V}$	$V_{DS} = 25\text{ V}, f = 1\text{ MHz}$	N-Ch	-	49		pF
		$V_{GS} = 0\text{ V}$	$V_{DS} = -25\text{ V}, f = 1\text{ MHz}$	P-Ch	-	110		
Gate Resistance	$R_g$	$f = 1\text{ MHz}$		N-Ch		4.6		Ω
				P-Ch		8.2		
<b>Switching characteristics<sup>3</sup></b>								
Total Gate Charge	$Q_g$	$V_{GS} = 10\text{ V}$	$V_{DD} = 20\text{ V}, I_D = 10\text{ A}$	N-Ch	-	25.5	38.3	nC
		$V_{GS} = -10\text{ V}$	$V_{DD} = -20\text{ V}, I_D = -10\text{ A}$	P-Ch	-	30.2	45	
Gate-Source Charge	$Q_{gs}$	$V_{GS} = 10\text{ V}$	$V_{DD} = 20\text{ V}, I_D = 10\text{ A}$	N-Ch	-	4.4	-	nC
		$V_{GS} = -10\text{ V}$	$V_{DSD} = -20\text{ V}, I_D = -10\text{ A}$	P-Ch	-	4.1	-	
Gate-Drain Charge	$Q_{gd}$	$V_{GS} = 10\text{ V}$	$V_{DS} = 20\text{ V}, I_D = 10\text{ A}$	N-Ch	-	4.3	-	nC
		$V_{GS} = -10\text{ V}$	$V_{DS} = -20\text{ V}, I_D = -10\text{ A}$	P-Ch	-	7.4	-	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 20\text{ V}, I_D = 10\text{ A}, V_{GS} = 10\text{ V}, R_g = 1\ \Omega$		N-Ch	-	8	12	ns
		$V_{DD} = -20\text{ V}, I_D = -10\text{ A}, V_{GS} = -10\text{ V}, R_g = 1\ \Omega$		P-Ch	-	7	11	
Rise Time	$t_r$	$V_{DD} = 20\text{ V}, I_D = 10\text{ A}, V_{GS} = 10\text{ V}, R_g = 1\ \Omega$		N-Ch	-	12	18	ns
		$V_{DD} = -20\text{ V}, I_D = -10\text{ A}, V_{GS} = -10\text{ V}, R_g = 1\ \Omega$		P-Ch	-	9	13	
Turn-Off Delay Time	$t_{d(off)}$	$V_{DD} = 20\text{ V}, I_D = 10\text{ A}, V_{GS} = 10\text{ V}, R_g = 1\ \Omega$		N-Ch	-	22	33	ns
		$V_{DD} = -20\text{ V}, I_D = -10\text{ A}, V_{GS} = -10\text{ V}, R_g = 1\ \Omega$		P-Ch	-	43	64	
Fall Time	$t_f$	$V_{DD} = 20\text{ V}, I_D = 10\text{ A}, V_{GS} = 10\text{ V}, R_g = 1\ \Omega$		N-Ch	-	10	16	ns
		$V_{DD} = -20\text{ V}, I_D = -10\text{ A}, V_{GS} = -10\text{ V}, R_g = 1\ \Omega$		P-Ch	-	19	28	
<b>Drain-Source Diode Characteristics</b>								
Forward Voltage <sup>2</sup>	$V_{SD}$	$I_S = 6.5\text{ A}$		N-Ch	-	0.79	1.2	V
		$I_S = -3.4\text{ A}$		P-Ch	-	-0.78	-1.2	
Continuous drain-source diode forward Current <sup>4</sup>	$I_S$			N-Ch		20	A	
				P-Ch		-20		
Pulsed Current <sup>1</sup>	$I_{SM}$			N-Ch	-	-	80	A
				P-Ch	-	-	-80	
Reverse recovery time	$T_{rr}$	$I_F = 20\text{ A}, dI/dt = 100\text{ A}/\mu\text{s}$		N-Ch		10	ns	
		$I_F = -20\text{ A}, dI/dt = 100\text{ A}/\mu\text{s}$		P-Ch		18		
Reverse recovery charge	$Q_{rr}$	$I_F = 20\text{ A}, dI/dt = 100\text{ A}/\mu\text{s}$		N-Ch		14	nC	
		$I_F = -20\text{ A}, dI/dt = 100\text{ A}/\mu\text{s}$		P-Ch		12		

## Notes:

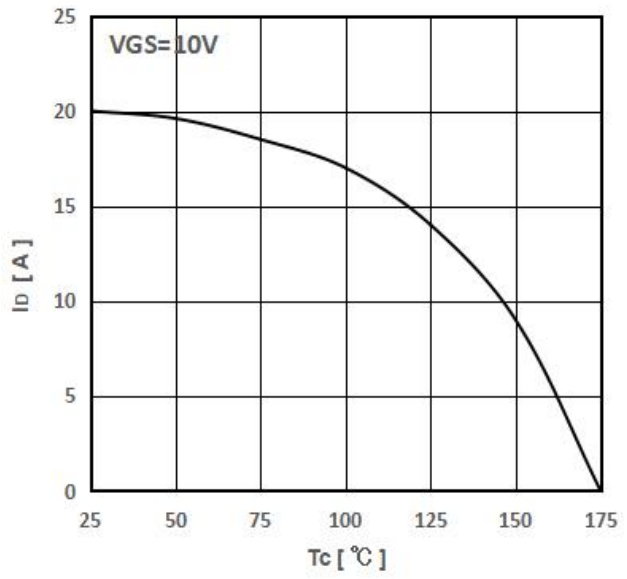
1. Pulse test; pulse width  $\leq 300\ \mu\text{s}$ , duty cycle  $\leq 2\%$ .
2. Guaranteed by design, not subject to production testing.
3. Independent of operating temperature.
4.  $T_C = 25^\circ\text{C}$  Limited only by maximum temperature allowed.

# N-Channel Typical Characteristics

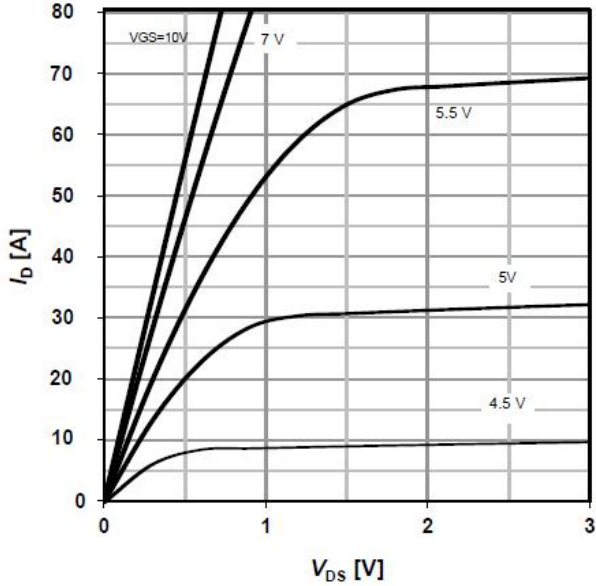
PD -- Tc



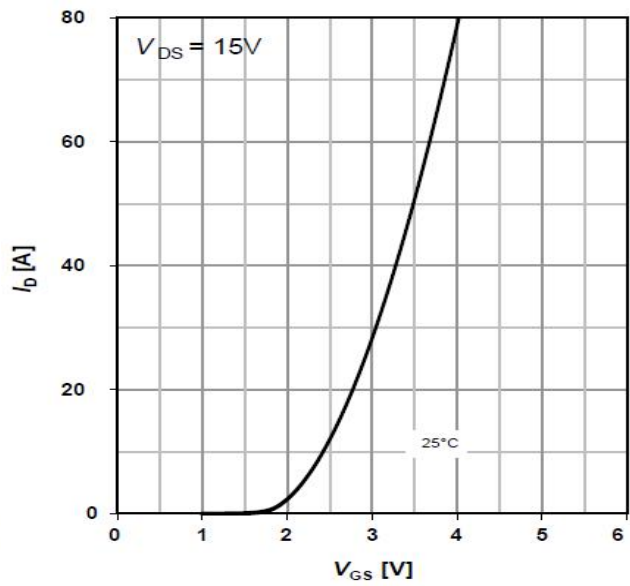
ID -- Tc



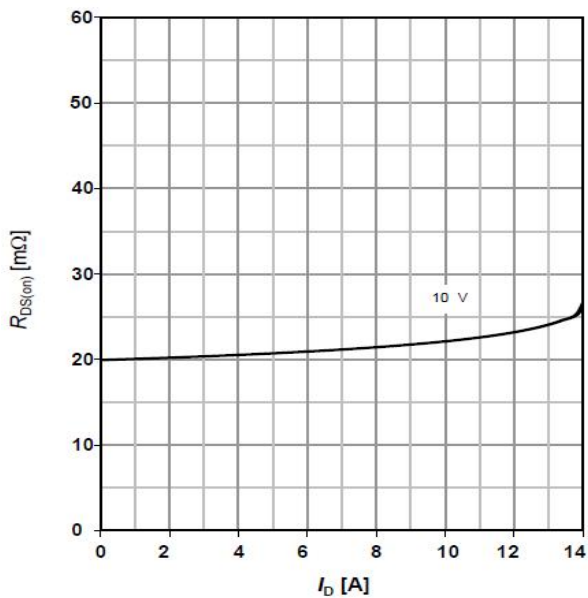
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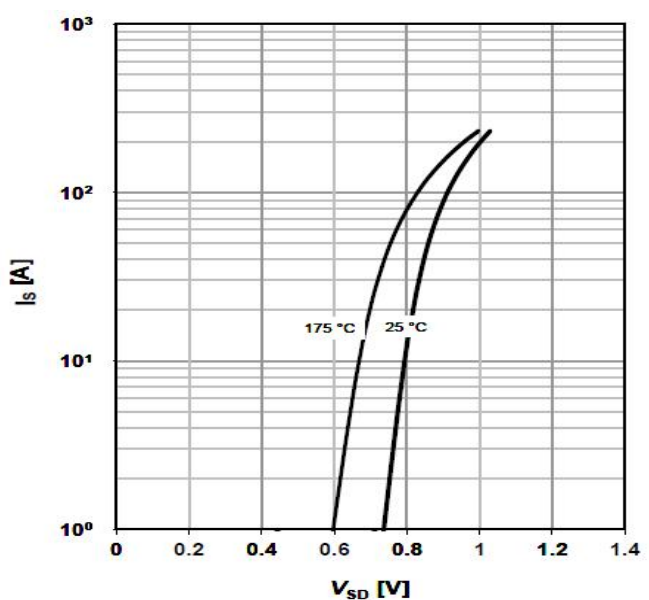
ID -- VGS



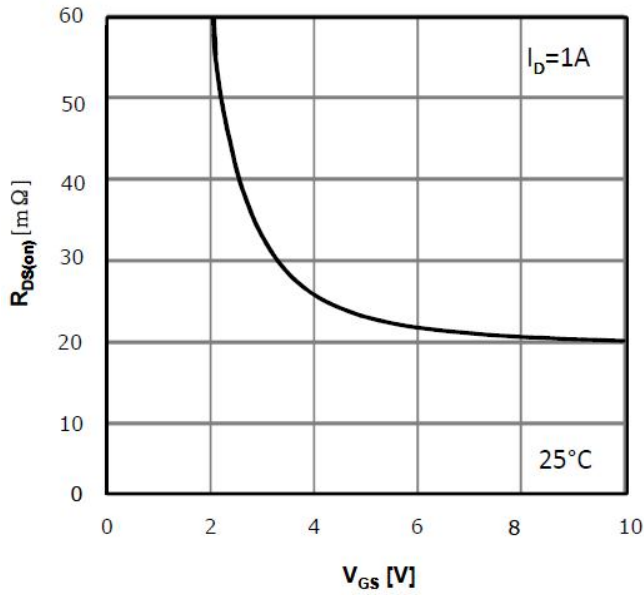
RDS(on) -- ID



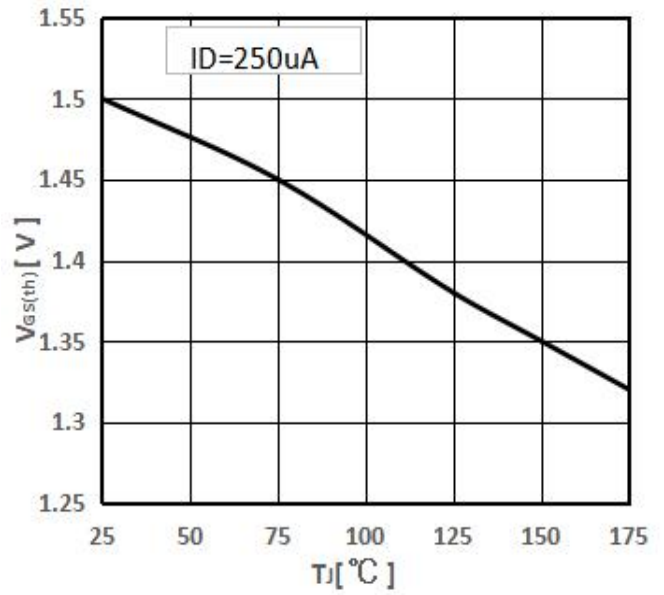
IS -- VSD



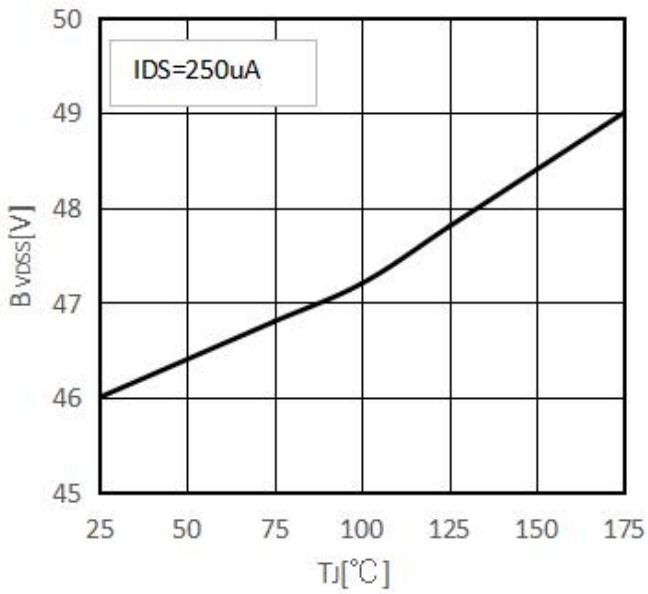
### RDS(on) -- VGS



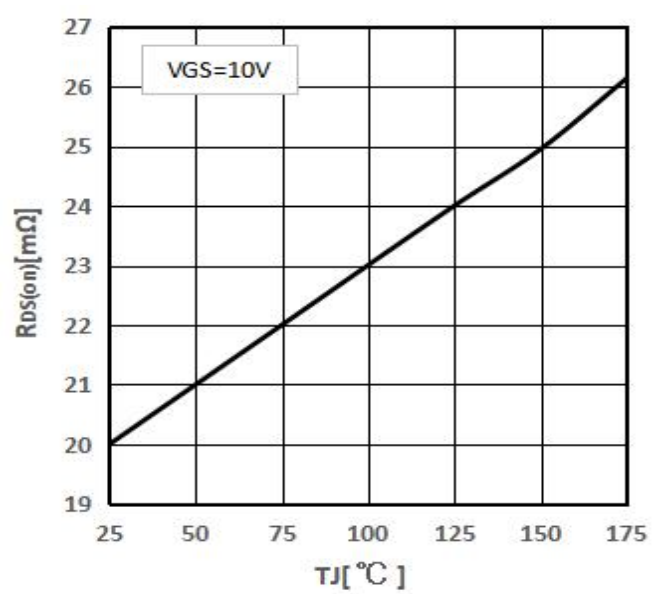
### Threshold Voltage



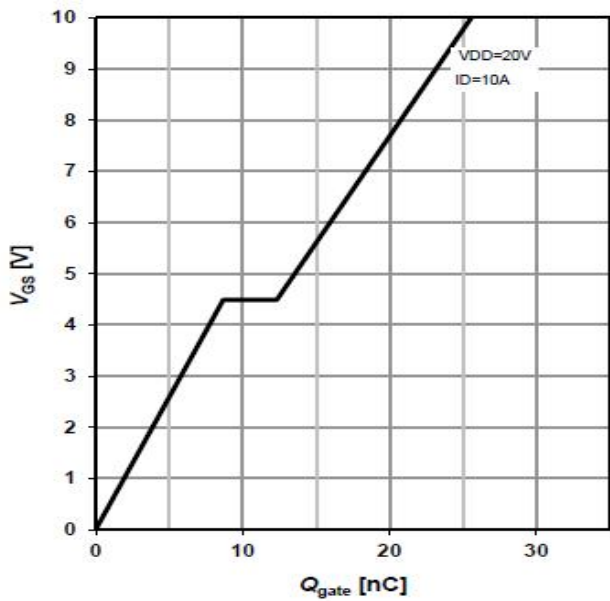
### Drain-source breakdown voltage



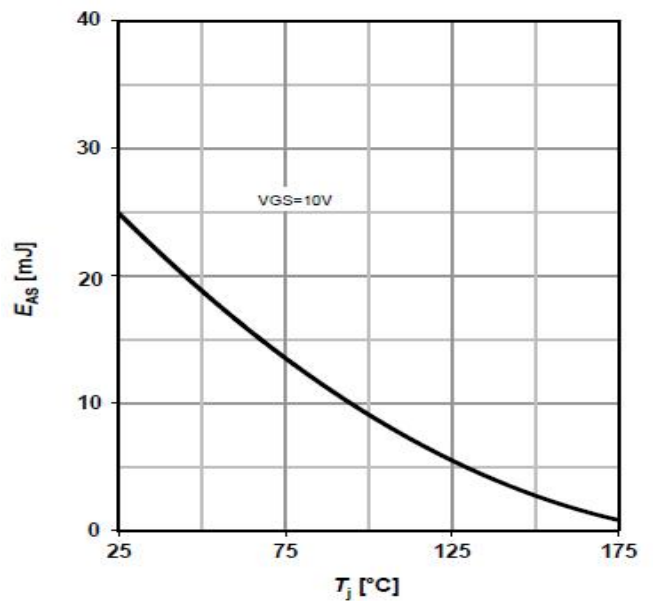
### RDS (on) -- Tj



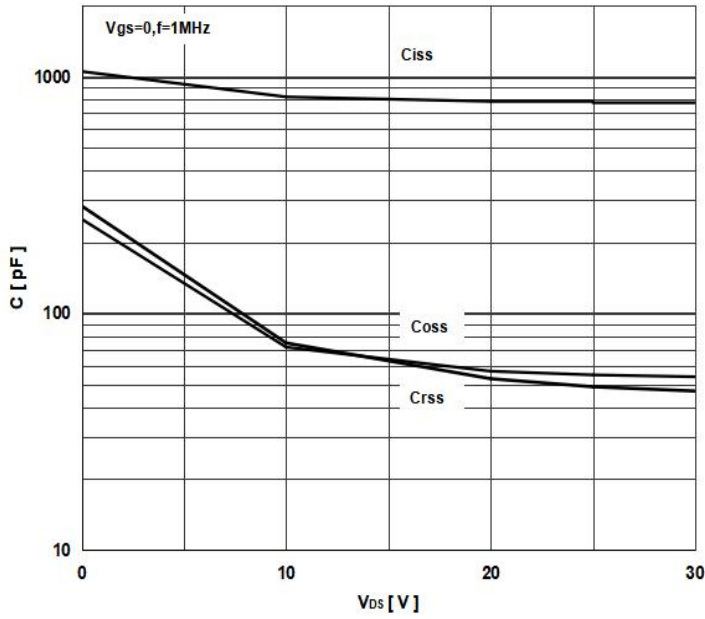
### Typ.gate charge



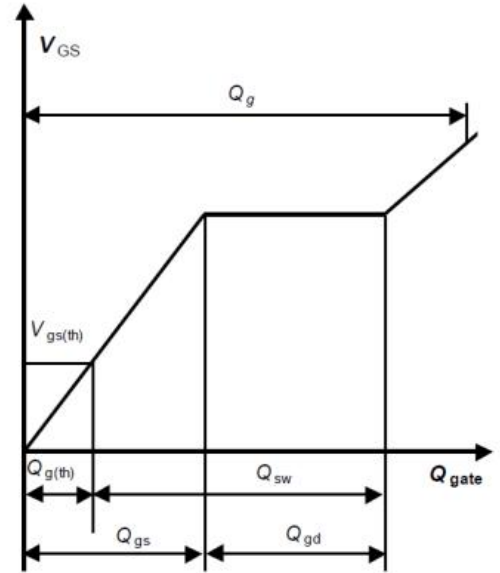
### Avalanche energy



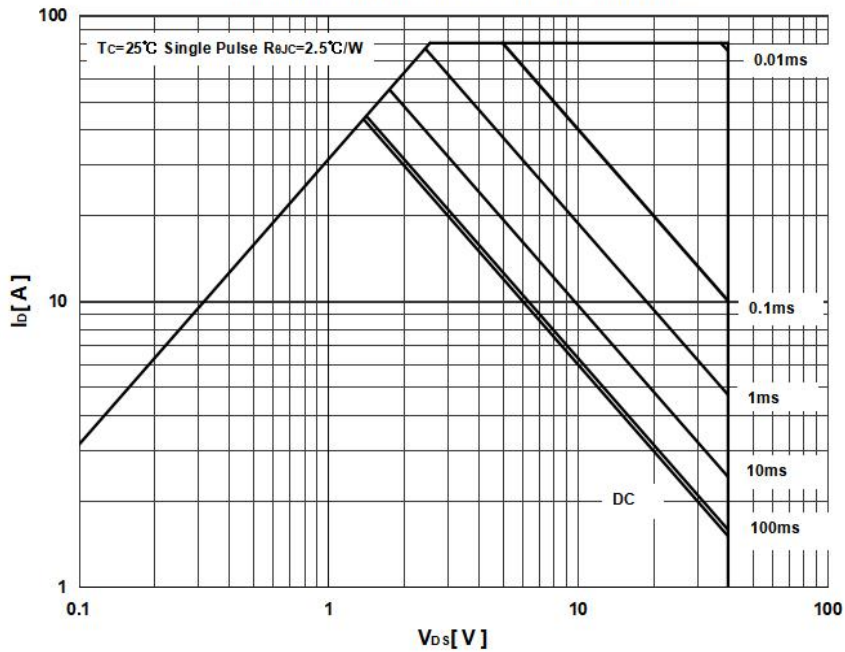
### Typ. capacitance



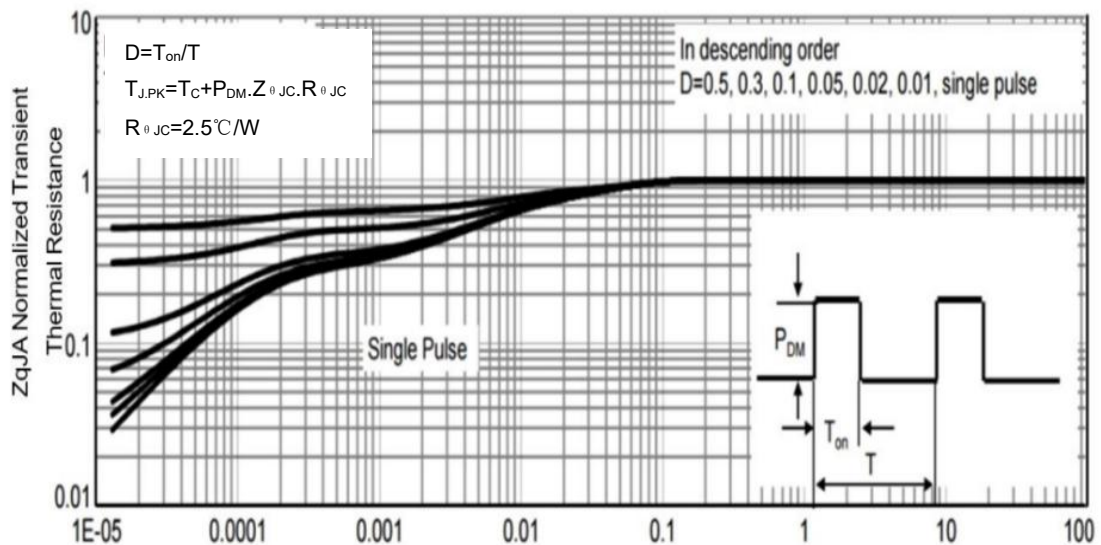
### Gate charge waveforms



### Maximum Forward Biased Safe Operating Area

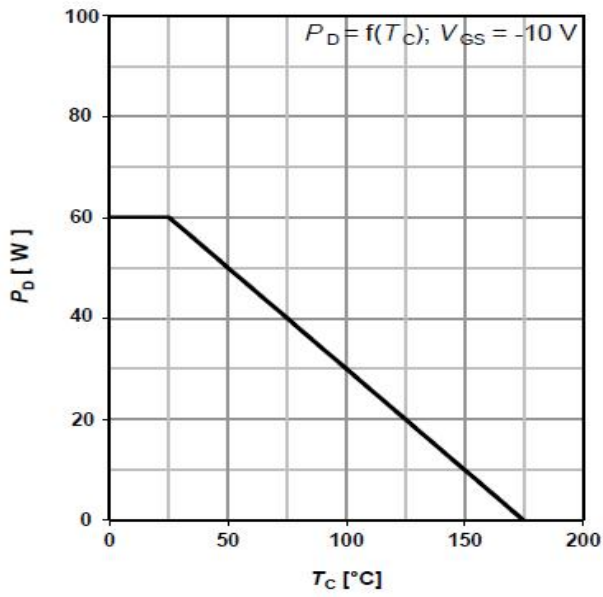


### Normalized Thermal Transient Impedance

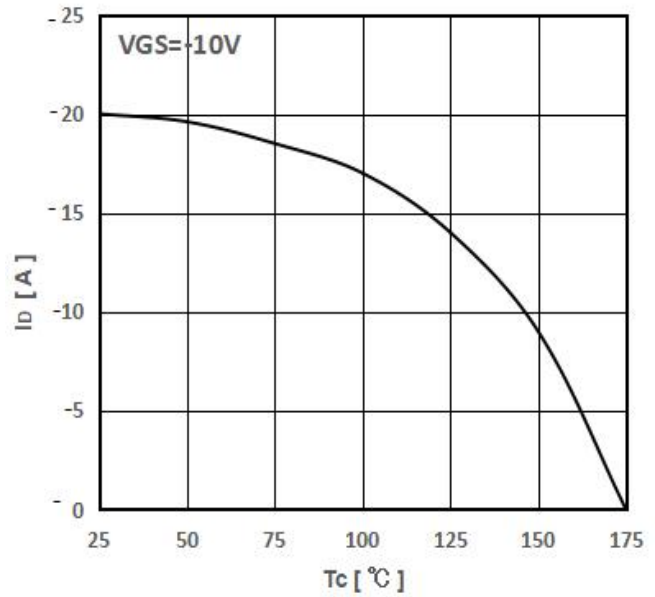


# P-Channel Typical Characteristics

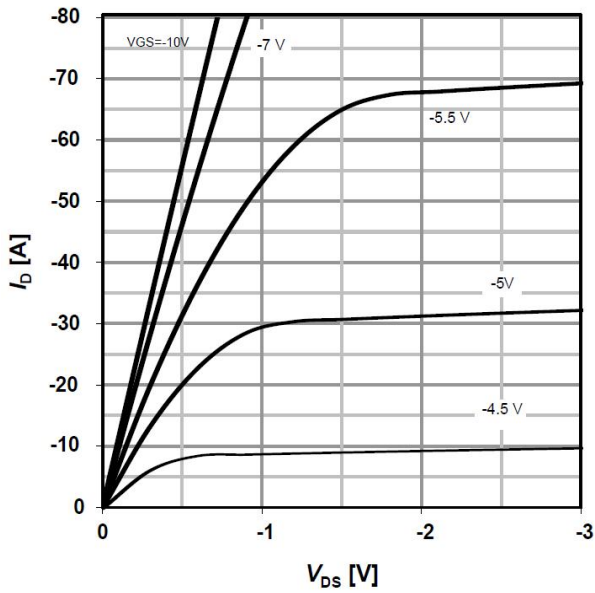
PD -- Tc



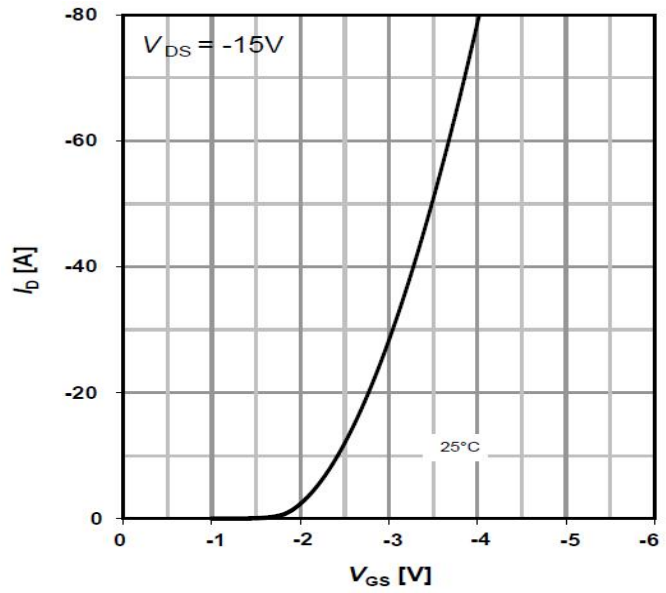
ID -- Tc



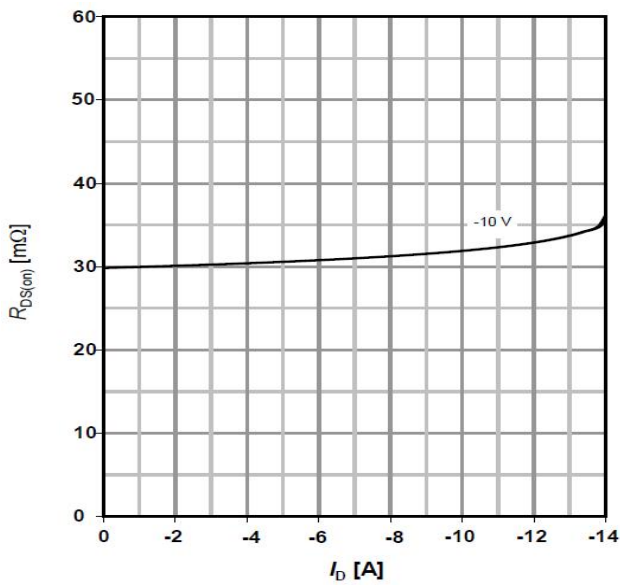
ID -- VDS



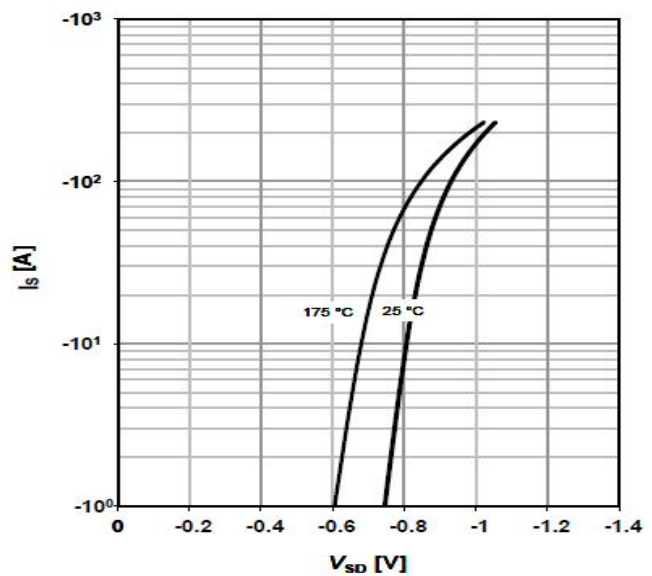
ID -- VGS



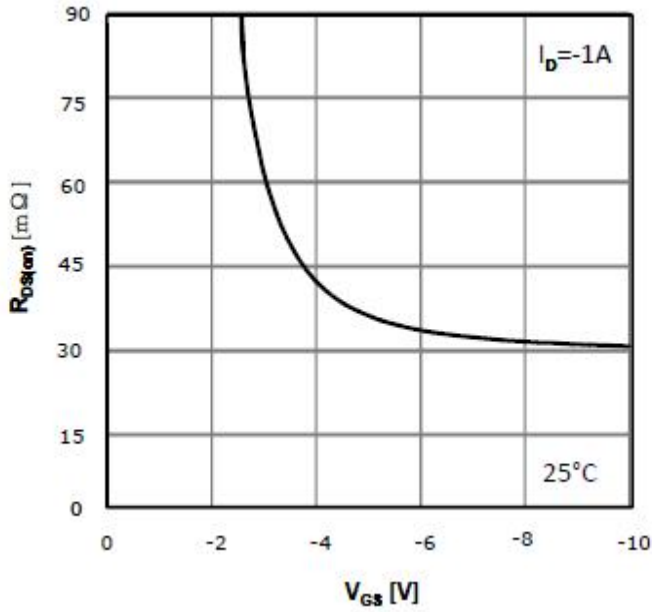
RDS(on) -- ID



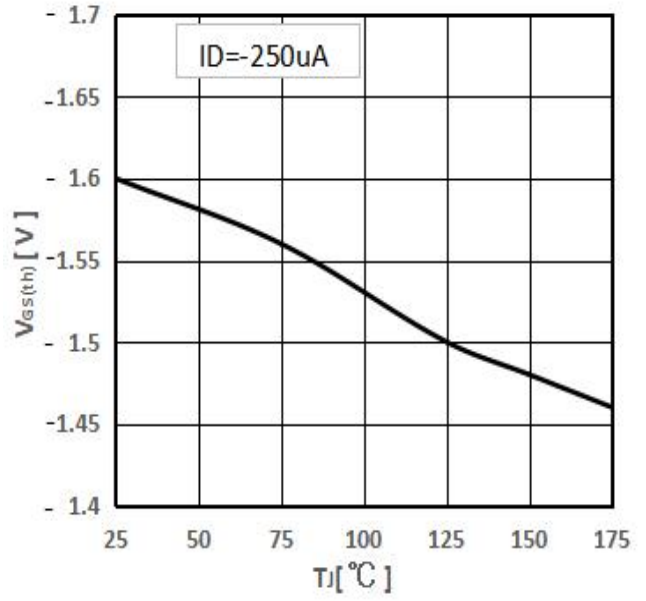
IS -- VSD



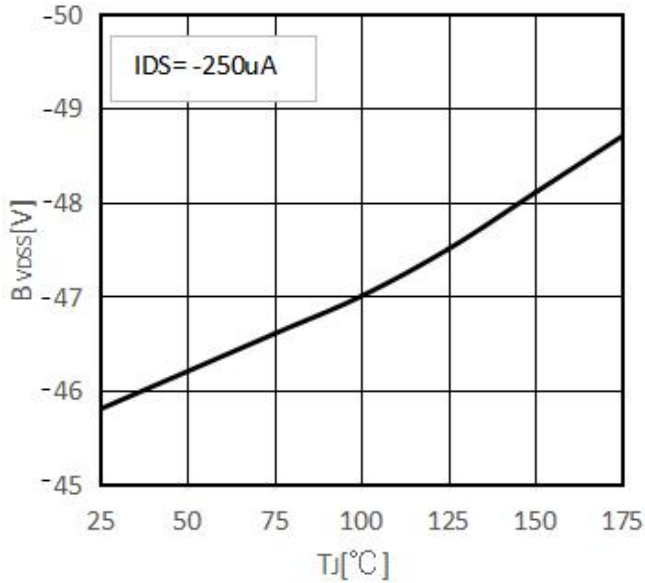
**RDS(on) -- VGS**



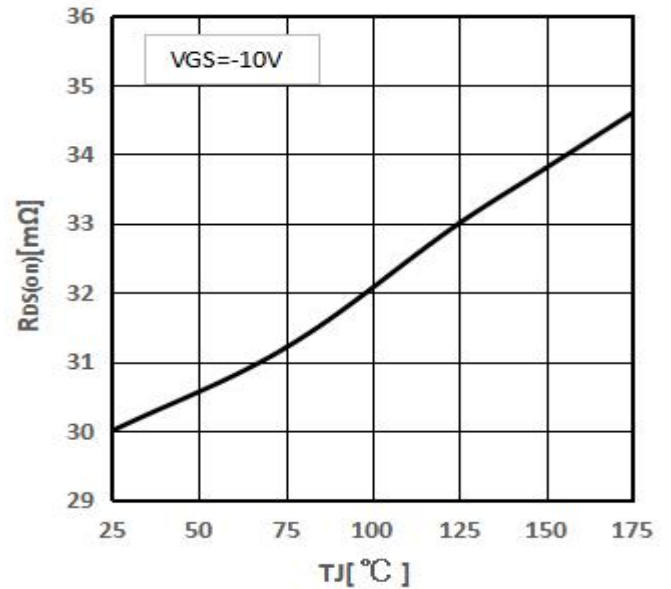
**Threshold Voltage**



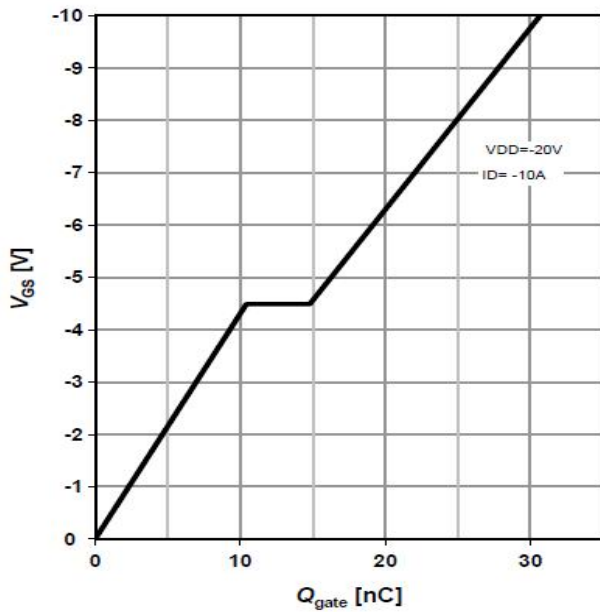
**Drain-source breakdown voltage**



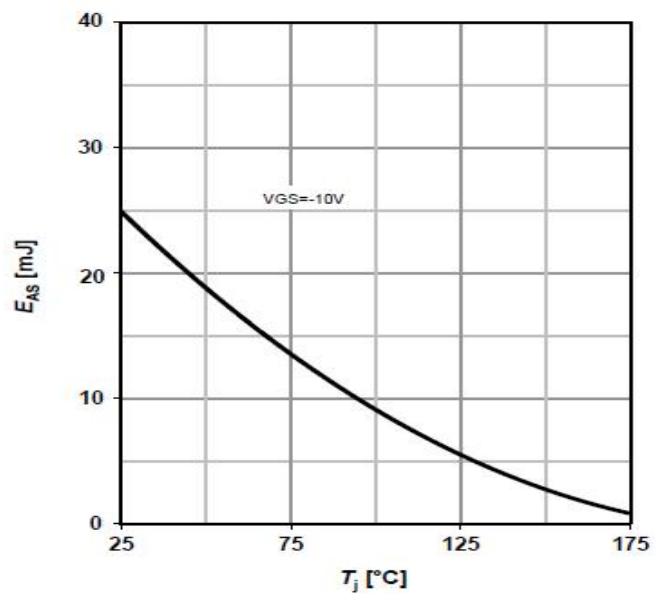
**RDS (on) -- Tj**



**Typ.gate charge**

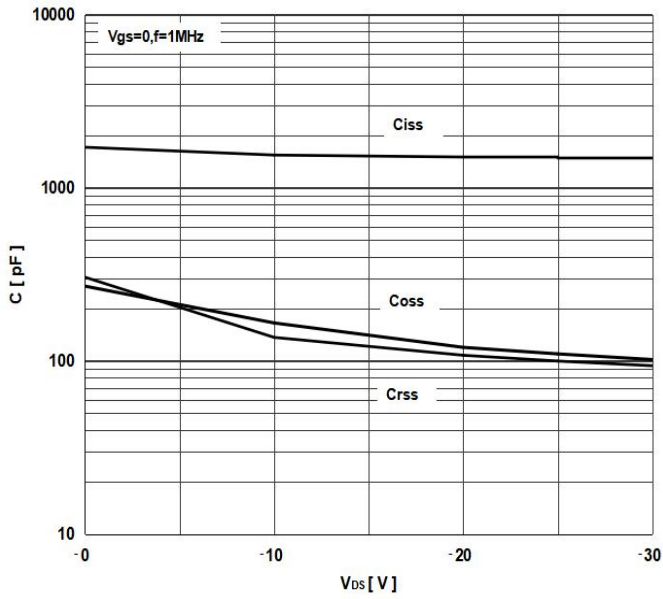


**Avalanche energy**

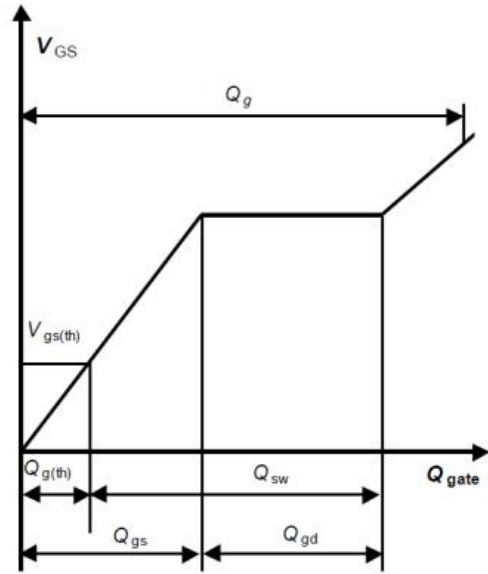




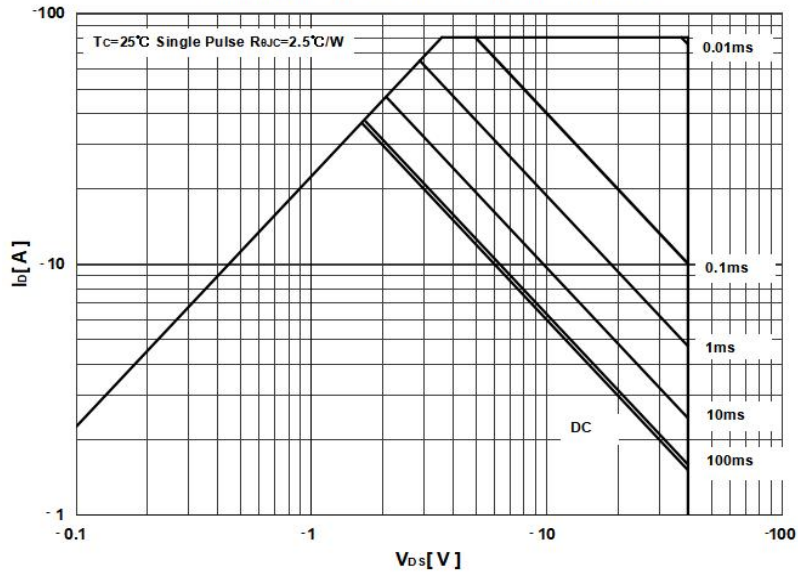
### Typ. capacitance



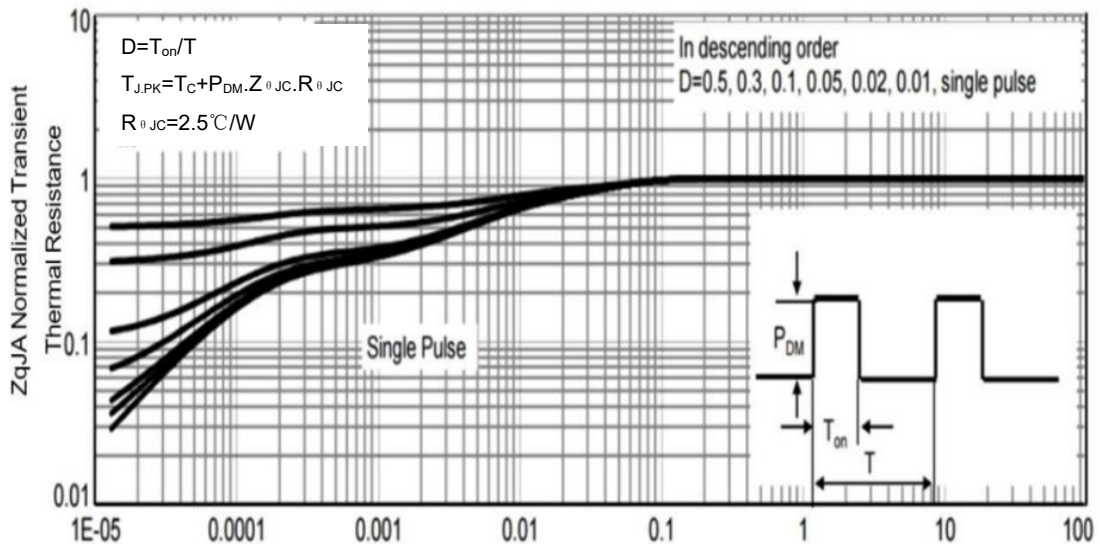
### Gate charge waveforms



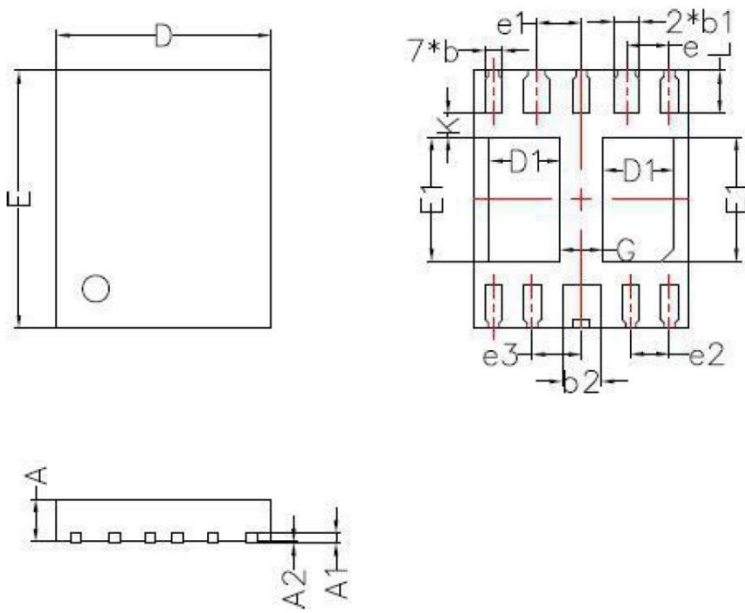
### Maximum Forward Biased Safe Operating Area



### Normalized Thermal Transient Impedance



## DFN5\*6-10L Package Outline Dimensions



Unit: mm

Package Dimensions			
Symbols	Min	Nom	Max
A	0.95	1.00	1.05
A1	0.203REF		
A2	0.00	0.02	0.05
D	4.90	5.00	5.10
E	5.90	6.00	6.10
D1	1.60	1.65	1.70
E1	2.85	2.90	2.95
L	0.95	1.00	1.05
b	0.35	0.40	0.45
b1	0.55	0.60	0.65
b2	0.85	0.90	0.95
K	0.50	0.55	0.60
G	0.95	1.00	1.05
e	1.00BSC		
e1	1.05BSC		
e2	0.90BSC		
e3	1.15BSC		

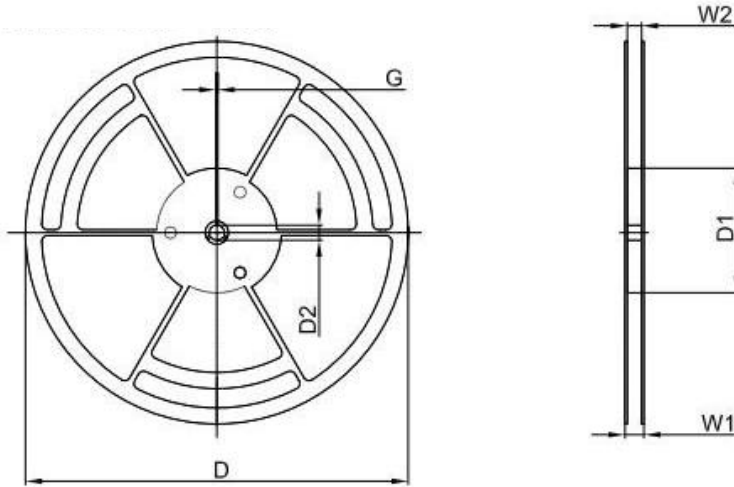
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## DFN5\*6-10L Tape and Reel

### DFN5\*6-10L Reel



Dimensions are in millimeter						
Reel Option	D	D1	D2	G	W1	W2
13"D1a	Ø330,00	100,00	13,00	1,90	17,60	12,40

REEL	Reel Size	Box	Box Size(mm)	Carton	Carton Size(mm)
5,000 pcs	13 inch	5,000 pcs	340×336×29	50,000 pcs	353×346×365

Date of change	Rev #	revise content
2022/12/12	A/0	/